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(54) Title: SEMICONDUCTOR DEVICE SUPPORT FOR BONDING

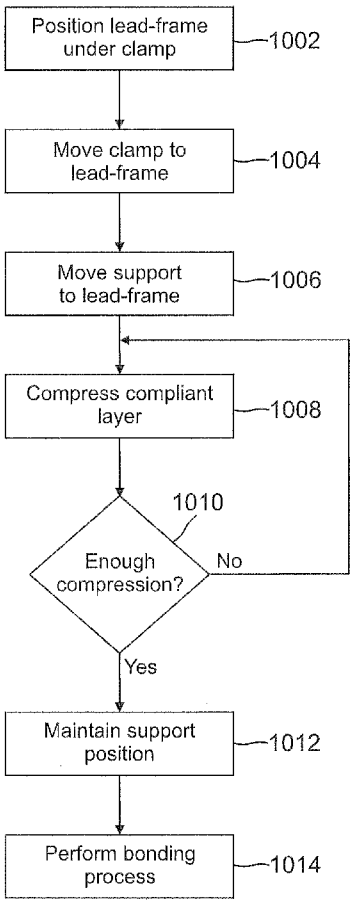


FIG. 10

(57) Abstract: In one embodiment, a support structure comprises a base, a compliant layer, and a protective layer which is used to secure a semiconductor device, such as a lead-frame, to a window clamp during a bonding process. The compliant layer distributes even loading over the surface of the semiconductor device while clamped. In other embodiments, the compliant layer may be segmented into individual portions corresponding with openings in the window clamp. The window clamp may also have a compliant layer and a protective layer and may be used with or without a compliant layer on the support structure. Features on the protective layer may be included to support structures of the semiconductor device.

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